PCF8574; PCF8574A

Remote 8-bit I/O expander for I²C-bus with interrupt

Rev. 5 — 27 May 2013 Product data sheet

1. General description

The PCF8574/74A provides general-purpose remote I/O expansion via the two-wire bidirectional I²C-bus (serial clock (SCL), serial data (SDA)).

The devices consist of eight quasi-bidirectional ports, 100 kHz I²C-bus interface, three hardware address inputs and interrupt output operating between 2.5 V and 6 V. The quasi-bidirectional port can be independently assigned as an input to monitor interrupt status or keypads, or as an output to activate indicator devices such as LEDs. System master can read from the input port or write to the output port through a single register.

The low current consumption of 2.5 μA (typical, static) is great for mobile applications and the latched output ports directly drive LEDs.

The PCF8574 and PCF8574A are identical, except for the different fixed portion of the slave address. The three hardware address pins allow eight of each device to be on the same I²C-bus, so there can be up to 16 of these I/O expanders PCF8574/74A together on the same I²C-bus, supporting up to 128 I/Os (for example, 128 LEDs).

The active LOW open-drain interrupt output ($\overline{INT}$) can be connected to the interrupt logic of the microcontroller and is activated when any input state differs from its corresponding input port register state. It is used to indicate to the microcontroller that an input state has changed and the device needs to be interrogated without the microcontroller continuously polling the input register via the I²C-bus.

The internal Power-On Reset (POR) initializes the I/Os as inputs with a weak internal pull-up 100 μA current source.

2. Features and benefits

- I²C-bus to parallel port expander
- 100 kHz I²C-bus interface (Standard-mode I²C-bus)
- Operating supply voltage 2.5 V to 6 V with non-overvoltage tolerant I/O held to V_{DD} with 100 μA current source
- 8-bit remote I/O pins that default to inputs at power-up
- Latched outputs directly drive LEDs
- Total package sink capability of 80 mA
- Active LOW open-drain interrupt output
- Eight programmable slave addresses using three address pins
- Low standby current (2.5 μA typical)
- −40 °C to +85 °C operation
- ESD protection exceeds 2000 V HBM per JESD22-A114 and 1000 V CDM per JESD22-C101

- Latch-up testing is done to JEDEC standard JESD78 which exceeds 100 mA
- Packages offered: DIP16, SO16, SSOP20

3. Applications

- LED signs and displays
- Servers
- Key pads
- Industrial control
- Medical equipment
- PLC
- Cellular telephones
- Mobile devices
- Gaming machines
- Instrumentation and test measurement

4. Ordering information

Table 1. Ordering information

Type number	Topside mark	Package		
		Name	Description	Version
PCF8574P	PCF8574P	DIP16	plastic dual in-line package; 16 leads (300 mil)	SOT38-4
PCF8574AP	PCF8574AP			
PCF8574T/3	PCF8574T	SO16	plastic small outline package; 16 leads; body width 7.5 mm	SOT162-1
PCF8574AT/3	PCF8574AT			
PCF8574TS/3	8574TS	SSOP20	plastic shrink small outline package; 20 leads; body width 4.4 mm	SOT266-1
PCF8574ATS/3	8574A			

4.1 Ordering options

Table 2. Ordering options

Type number	Orderable part number	Package	Packing method	Minimum order quantity	Temperature range
PCF8574P	PCF8574P,112	DIP16	Standard marking * IC's tube - DSC bulk pack	1000	T_{amb} = −40 °C to +85 °C
PCF8574AP	PCF8574AP,112	DIP16	Standard marking * IC's tube - DSC bulk pack	1000	T_{amb} = −40 °C to +85 °C
PCF8574T/3	PCF8574T/3,512	SO16	Standard marking * tube dry pack	1920	T_{amb} = −40 °C to +85 °C
	PCF8574T/3,518	SO16	Reel 13" Q1/T1 *standard mark SMD dry pack	1000	T_{amb} = −40 °C to +85 °C
PCF8574AT/3	PCF8574AT/3,512	SO16	Standard marking * tube dry pack	1920	T_{amb} = −40 °C to +85 °C
	PCF8574AT/3,518	SO16	Reel 13" Q1/T1 *standard mark SMD dry pack	1000	T_{amb} = −40 °C to +85 °C

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Table 2. Ordering options *...continued*

Type number	Orderable part number	Package	Packing method	Minimum order quantity	Temperature range
PCF8574TS/3	PCF8574TS/3,112	SSOP20	Standard marking * IC's tube - DSC bulk pack	1350	T_{amb} = −40 °C to +85 °C
	PCF8574TS/3,118	SSOP20	Reel 13" Q1/T1 *standard mark SMD	2500	T_{amb} = −40 °C to +85 °C
PCF8574ATS/3	PCF8574ATS/3,118	SSOP20	Reel 13" Q1/T1 *standard mark SMD	2500	T_{amb} = −40 °C to +85 °C

5. Block diagram

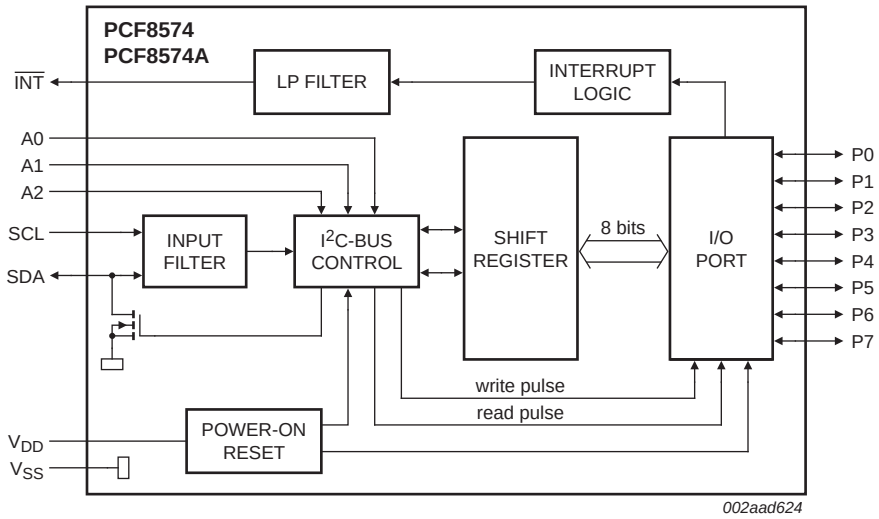

Fig 1. Block diagram

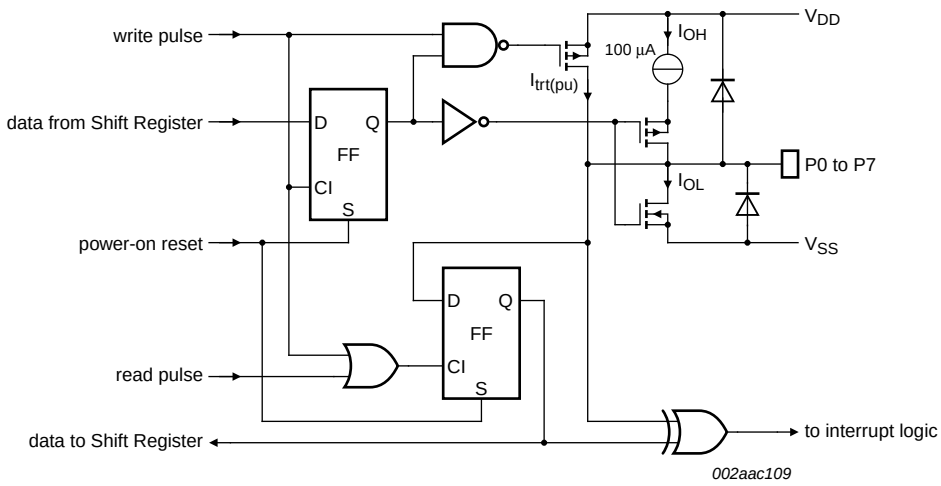

Fig 2. Simplified schematic diagram of P0 to P7

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6. Pinning information

6.1 Pinning

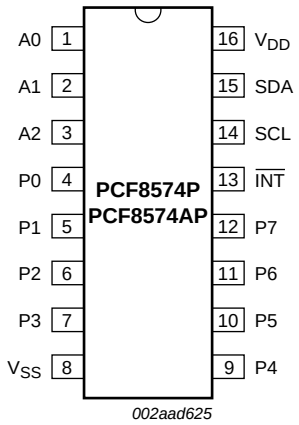

Fig 3. Pin configuration for DIP16

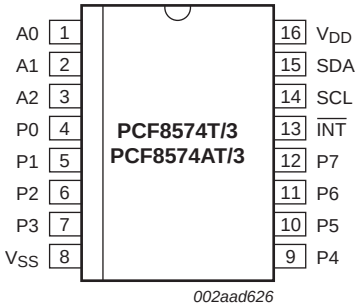

Fig 4. Pin configuration for SO16

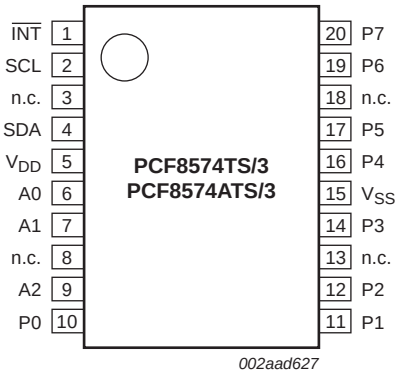

Fig 5. Pin configuration for SSOP20

6.2 Pin description

Table 3. Pin description

Symbol	Pin		Description
	DIP16, SO16	SSOP20	
A0	1	6	address input 0
A1	2	7	address input 1
A2	3	9	address input 2
P0	4	10	quasi-bidirectional I/O 0
P1	5	11	quasi-bidirectional I/O 1
P2	6	12	quasi-bidirectional I/O 2
P3	7	14	quasi-bidirectional I/O 3
V_{SS}	8	15	supply ground
P4	9	16	quasi-bidirectional I/O 4
P5	10	17	quasi-bidirectional I/O 5
P6	11	19	quasi-bidirectional I/O 6
P7	12	20	quasi-bidirectional I/O 7
$\overline{INT}$	13	1	interrupt output (active LOW)
SCL	14	2	serial clock line
SDA	15	4	serial data line
V_{DD}	16	5	supply voltage
n.c.	-	3, 8, 13, 18	not connected

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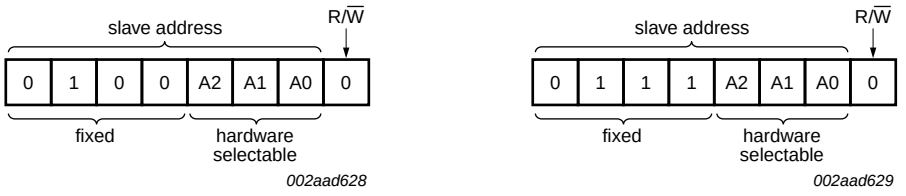
7. Functional description

Refer to Figure 1 “Block diagram”.

7.1 Device address

Following a START condition, the bus master must send the address of the slave it is accessing and the operation it wants to perform (read or write). The address format of the PCF8574/74A is shown in Figure 6. Slave address pins A2, A1 and A0 are held HIGH or LOW to choose one of eight slave addresses. To conserve power, no internal pull-up resistors are incorporated on A2, A1 or A0, so they must be externally held HIGH or LOW. The address pins (A2, A1, A0) can connect to V_{DD} or V_{SS} directly or through resistors.



a. PCF8574 b. PCF8574A

Fig 6. PCF8574 and PCF8574A slave addresses

The last bit of the first byte defines the operation to be performed. When set to logic 1 a read is selected, while a logic 0 selects a write operation (write operation is shown in Figure 6).

7.1.1 Address maps

The PCF8574 and PCF8574A are functionally the same, but have a different fixed portion (A6 to A3) of the slave address. This allows eight of the PCF8574 and eight of the PCF8574A to be on the same I²C-bus without address conflict.

Table 4. PCF8574 address map

Pin connectivity			Address of PCF8574								Address byte value		7-bit hexadecimal address without R/W
A2	A1	A0	A6	A5	A4	A3	A2	A1	A0	R/W	Write	Read	
V_{SS}	V_{SS}	V_{SS}	0	1	0	0	0	0	0	-	40h	41h	20h
V_{SS}	V_{SS}	V_{DD}	0	1	0	0	0	0	1	-	42h	43h	21h
V_{SS}	V_{DD}	V_{SS}	0	1	0	0	0	1	0	-	44h	45h	22h
V_{SS}	V_{DD}	V_{DD}	0	1	0	0	0	1	1	-	46h	47h	23h
V_{DD}	V_{SS}	V_{SS}	0	1	0	0	1	0	0	-	48h	49h	24h
V_{DD}	V_{SS}	V_{DD}	0	1	0	0	1	0	1	-	4Ah	4Bh	25h
V_{DD}	V_{DD}	V_{SS}	0	1	0	0	1	1	0	-	4Ch	4Dh	26h
V_{DD}	V_{DD}	V_{DD}	0	1	0	0	1	1	1	-	4Eh	4Fh	27h

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Table 5. PCF8574A address map

Pin connectivity			Address of PCF8574A								Address byte value		7-bit hexadecimal address without R/W
A2	A1	A0	A6	A5	A4	A3	A2	A1	A0	R/$\overline{W}$	Write	Read	
V_{SS}	V_{SS}	V_{SS}	0	1	1	1	0	0	0	-	70h	71h	38h
V_{SS}	V_{SS}	V_{DD}	0	1	1	1	0	0	1	-	72h	73h	39h
V_{SS}	V_{DD}	V_{SS}	0	1	1	1	0	1	0	-	74h	75h	3Ah
V_{SS}	V_{DD}	V_{DD}	0	1	1	1	0	1	1	-	76h	77h	3Bh
V_{DD}	V_{SS}	V_{SS}	0	1	1	1	1	0	0	-	78h	79h	3Ch
V_{DD}	V_{SS}	V_{DD}	0	1	1	1	1	0	1	-	7Ah	7Bh	3Dh
V_{DD}	V_{DD}	V_{SS}	0	1	1	1	1	1	0	-	7Ch	7Dh	3Eh
V_{DD}	V_{DD}	V_{DD}	0	1	1	1	1	1	1	-	7Eh	7Fh	3Fh

8. I/O programming

8.1 Quasi-bidirectional I/Os

A quasi-bidirectional I/O is an input or output port without using a direction control register. Whenever the master reads the register, the value returned to master depends on the actual voltage or status of the pin. At power on, all the ports are HIGH with a weak 100 μA internal pull-up to V_{DD}, but can be driven LOW by an internal transistor, or an external signal. The I/O ports are entirely independent of each other, but each I/O octal is controlled by the same read or write data byte.

Advantages of the quasi-bidirectional I/O over totem pole I/O include:

- Better for driving LEDs since the p-channel (transistor to V_{DD}) is small, which saves die size and therefore cost. LED drive only requires an internal transistor to ground, while the LED is connected to V_{DD} through a current-limiting resistor. Totem pole I/O have both n-channel and p-channel transistors, which allow solid HIGH and LOW output levels without a pull-up resistor — good for logic levels.
- Simpler architecture — only a single register and the I/O can be both input and output at the same time. Totem pole I/O have a direction register that specifies the port pin direction and it is always in that configuration unless the direction is explicitly changed.
- Does not require a command byte. The simplicity of one register (no need for the pointer register or, technically, the command byte) is an advantage in some embedded systems where every byte counts because of memory or bandwidth limitations.

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There is only one register to control four possibilities of the port pin: Input HIGH, input LOW, output HIGH, or output LOW.

Input HIGH: The master needs to write 1 to the register to set the port as an input mode if the device is not in the default power-on condition. The master reads the register to check the input status. If the external source pulls the port pin up to V_{DD} or drives logic 1, then the master will read the value of 1.

Input LOW: The master needs to write 1 to the register to set the port to input mode if the device is not in the default power-on condition. The master reads the register to check the input status. If the external source pulls the port pin down to V_{SS} or drives logic 0, which sinks the weak 100 μA current source, then the master will read the value of 0.

Output HIGH: The master writes 1 to the register. There is an additional 'accelerator' or strong pull-up current when the master sets the port HIGH. The additional strong pull-up is only active during the HIGH time of the acknowledge clock cycle. This accelerator current helps the port's 100 μA current source make a faster rising edge into a heavily loaded output, but only at the start of the acknowledge clock cycle to avoid bus contention if an external signal is pulling the port LOW to V_{SS}/driving the port with logic 0 at the same time. After the half clock cycle there is only the 100 μA current source to hold the port HIGH.

Output LOW: The master writes 0 to the register. There is a strong current sink transistor that holds the port pin LOW. A large current may flow into the port, which could potentially damage the part if the master writes a 0 to the register and an external source is pulling the port HIGH at the same time.

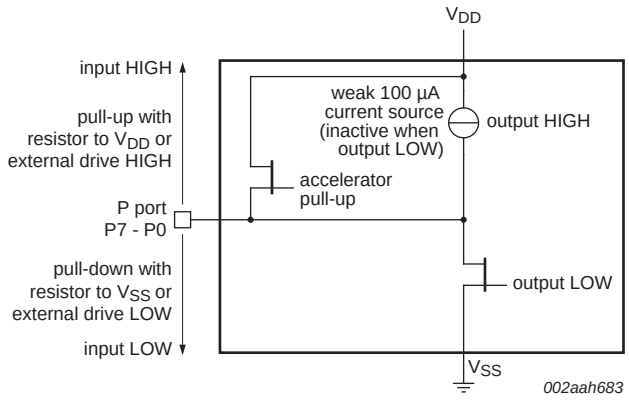

Fig 7. Simple quasi-bidirectional I/O

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8.2 Writing to the port (Output mode)

The master (microcontroller) sends the START condition and slave address setting the last bit of the address byte to logic 0 for the write mode. The PCF8574/74A acknowledges and the master then sends the data byte for P7 to P0 to the port register. As the clock line goes HIGH, the 8-bit data is presented on the port lines after it has been acknowledged by the PCF8574/74A. If a LOW is written, the strong pull-down turns on and stays on. If a HIGH is written, the strong pull-up turns on for ½ of the clock cycle, then the line is held HIGH by the weak current source. The master can then send a STOP or ReSTART condition or continue sending data. The number of data bytes that can be sent successively is not limited and the previous data is overwritten every time a data byte has been sent and acknowledged.

Ensure a logic 1 is written for any port that is being used as an input to ensure the strong external pull-down is turned off.

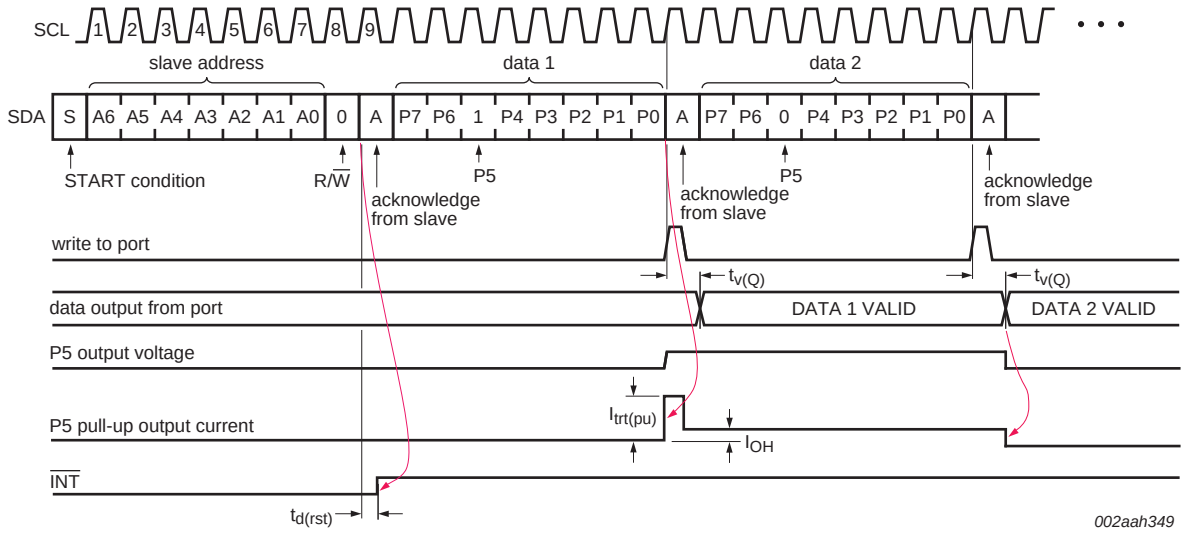

Fig 8. Write mode (output)

Simple code WRITE mode:

<S> <slave address + write> <**ACK**> <data out> <**ACK**> <data out> <**ACK**> ... <data out> <**ACK**> <P>

Remark: Bold type = generated by slave device.

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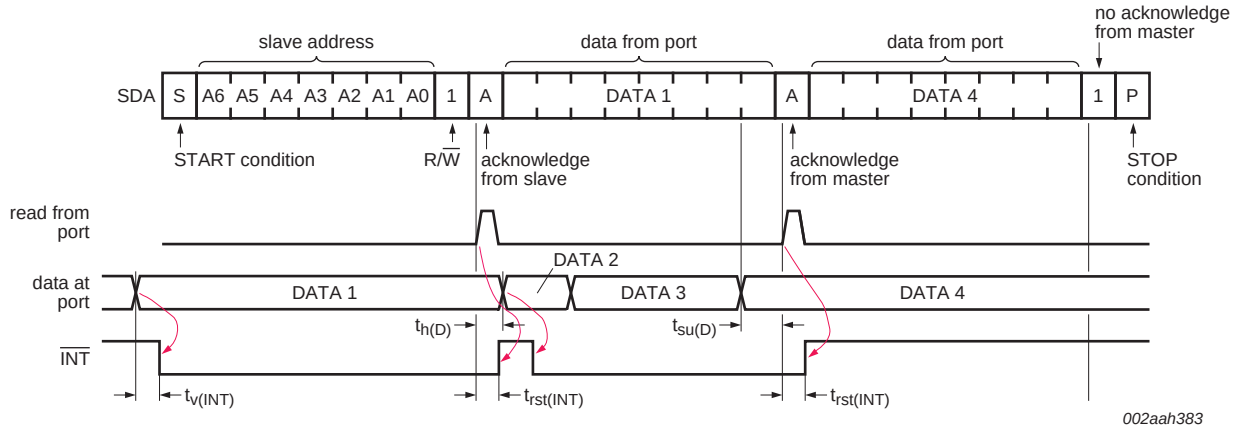
8.3 Reading from a port (Input mode)

The port must have been previously written to logic 1, which is the condition after power-on reset. To enter the Read mode the master (microcontroller) addresses the slave device and sets the last bit of the address byte to logic 1 (address byte read). The slave will acknowledge and then send the data byte to the master. The master will NACK and then send the STOP condition or ACK and read the input register again.

The read of any pin being used as an output will indicate HIGH or LOW depending on the actual state of the pin.

If the data on the input port changes faster than the master can read, this data may be lost. The DATA 2 and DATA3 are lost because these data did not meet the setup time and hold time (see Figure 9).



A LOW-to-HIGH transition of SDA while SCL is HIGH is defined as the STOP condition (P). Transfer of data can be stopped at any moment by a STOP condition. When this occurs, data present at the last acknowledge phase is valid (output mode). Input data is lost.

Fig 9. Read mode (input)

Simple code for Read mode:

<S> <slave address + read> <**ACK**> <**data in**> <ACK> ... <**data in**> <ACK> <**data in**> <NACK> <P>

Remark: Bold type = generated by slave device.

8.4 Power-on reset

When power is applied to V_{DD}, an internal Power-On Reset (POR) holds the PCF8574/74A in a reset condition until V_{DD} has reached V_{POR}. At that point, the reset condition is released and the PCF8574/74A registers and I²C-bus/SMBus state machine will initialize to their default states of all I/Os to inputs with weak current source to V_{DD}. Thereafter V_{DD} must be lowered below V_{POR} and back up to the operation voltage for power-on reset cycle.

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8.5 Interrupt output ($\overline{INT}$)

The PCF8574/74A provides an open-drain output ($\overline{INT}$) which can be fed to a corresponding input of the microcontroller (see Figure 10). As soon as a port input is changed, the $\overline{INT}$ will be active (LOW) and notify the microcontroller.

An interrupt is generated at any rising or falling edge of the port inputs. After time $t_{v(Q)}$, the signal $\overline{INT}$ is valid.

The interrupt will reset to HIGH when data on the port is changed to the original setting or data is read or written by the master.

In the Write mode, the interrupt may be reset (HIGH) on the rising edge of the acknowledge bit of the address byte and also on the rising edge of the write to port pulse. The interrupt will always be reset (HIGH) on the falling edge of the write to port pulse (see Figure 8).

The interrupt is reset (HIGH) in the Read mode on the rising edge of the read from port pulse (see Figure 9).

During the interrupt reset, any I/O change close to the read or write pulse may not generate an interrupt, or the interrupt will have a very short pulse. After the interrupt is reset, any change in I/Os will be detected and transmitted as an $\overline{INT}$.

At power-on reset all ports are in Input mode and the initial state of the ports is HIGH, therefore, for any port pin that is pulled LOW or driven LOW by external source, the interrupt output will be active (output LOW).

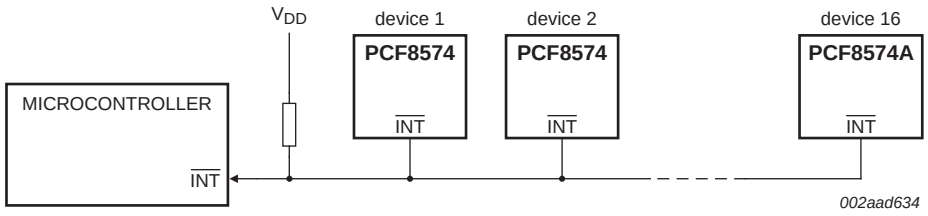

Fig 10. Application of multiple PCF8574/74As with interrupt

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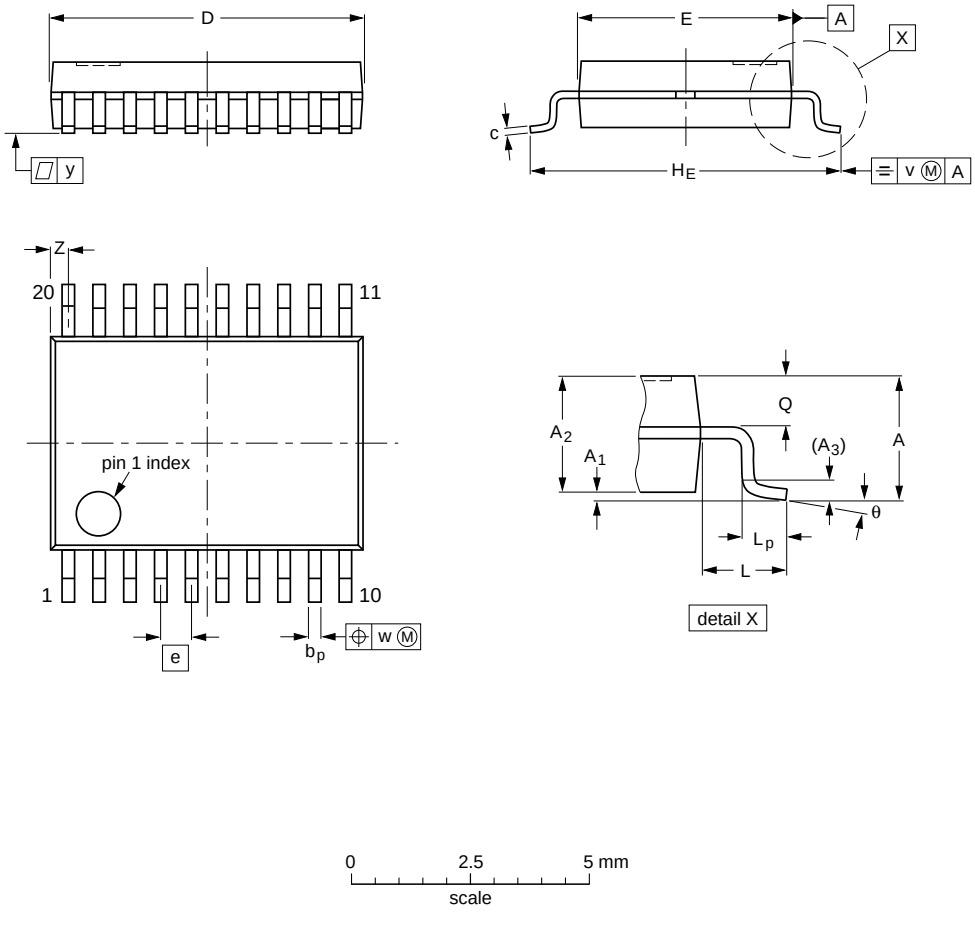
SSOP20: plastic shrink small outline package; 20 leads; body width 4.4 mm **SOT266-1**



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	$D^{(1)}$	$E^{(1)}$	e	H_E	L	L_p	Q	v	w	y	$Z^{(1)}$	θ
mm	1.5	0.15 0	1.4 1.2	0.25	0.32 0.20	0.20 0.13	6.6 6.4	4.5 4.3	0.65	6.6 6.2	1	0.75 0.45	0.65 0.45	0.2	0.13	0.1	0.48 0.18	10^o 0^o

Note

1. Plastic or metal protrusions of 0.20 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT266-1		MO-152				~~99-12-27~~ 03-02-19

Fig 20. Package outline SOT266-1 (SSOP20)

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16. Handling information

All input and output pins are protected against ElectroStatic Discharge (ESD) under normal handling. When handling ensure that the appropriate precautions are taken as described in *JESD625-A* or equivalent standards.

17. Soldering of SMD packages

This text provides a very brief insight into a complex technology. A more in-depth account of soldering ICs can be found in Application Note *AN10365 "Surface mount reflow soldering description"*.

17.1 Introduction to soldering

Soldering is one of the most common methods through which packages are attached to Printed Circuit Boards (PCBs), to form electrical circuits. The soldered joint provides both the mechanical and the electrical connection. There is no single soldering method that is ideal for all IC packages. Wave soldering is often preferred when through-hole and Surface Mount Devices (SMDs) are mixed on one printed wiring board; however, it is not suitable for fine pitch SMDs. Reflow soldering is ideal for the small pitches and high densities that come with increased miniaturization.

17.2 Wave and reflow soldering

Wave soldering is a joining technology in which the joints are made by solder coming from a standing wave of liquid solder. The wave soldering process is suitable for the following:

- Through-hole components
- Leaded or leadless SMDs, which are glued to the surface of the printed circuit board

Not all SMDs can be wave soldered. Packages with solder balls, and some leadless packages which have solder lands underneath the body, cannot be wave soldered. Also, leaded SMDs with leads having a pitch smaller than ~0.6 mm cannot be wave soldered, due to an increased probability of bridging.

The reflow soldering process involves applying solder paste to a board, followed by component placement and exposure to a temperature profile. Leaded packages, packages with solder balls, and leadless packages are all reflow solderable.

Key characteristics in both wave and reflow soldering are:

- Board specifications, including the board finish, solder masks and vias
- Package footprints, including solder thieves and orientation
- The moisture sensitivity level of the packages
- Package placement
- Inspection and repair
- Lead-free soldering versus SnPb soldering

17.3 Wave soldering

Key characteristics in wave soldering are:

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- Process issues, such as application of adhesive and flux, clinching of leads, board transport, the solder wave parameters, and the time during which components are exposed to the wave
- Solder bath specifications, including temperature and impurities

17.4 Reflow soldering

Key characteristics in reflow soldering are:

- Lead-free versus SnPb soldering; note that a lead-free reflow process usually leads to higher minimum peak temperatures (see Figure 21) than a SnPb process, thus reducing the process window
- Solder paste printing issues including smearing, release, and adjusting the process window for a mix of large and small components on one board
- Reflow temperature profile; this profile includes preheat, reflow (in which the board is heated to the peak temperature) and cooling down. It is imperative that the peak temperature is high enough for the solder to make reliable solder joints (a solder paste characteristic). In addition, the peak temperature must be low enough that the packages and/or boards are not damaged. The peak temperature of the package depends on package thickness and volume and is classified in accordance with Table 11 and 12

Table 11. SnPb eutectic process (from J-STD-020D)

Package thickness (mm)	Package reflow temperature (°C)	
	Volume (mm³)	
	< 350	≥ 350
< 2.5	235	220
≥ 2.5	220	220

Table 12. Lead-free process (from J-STD-020D)

Package thickness (mm)	Package reflow temperature (°C)		
	Volume (mm³)		
	< 350	350 to 2000	> 2000
< 1.6	260	260	260
1.6 to 2.5	260	250	245
> 2.5	250	245	245

Moisture sensitivity precautions, as indicated on the packing, must be respected at all times.

Studies have shown that small packages reach higher temperatures during reflow soldering, see Figure 21.

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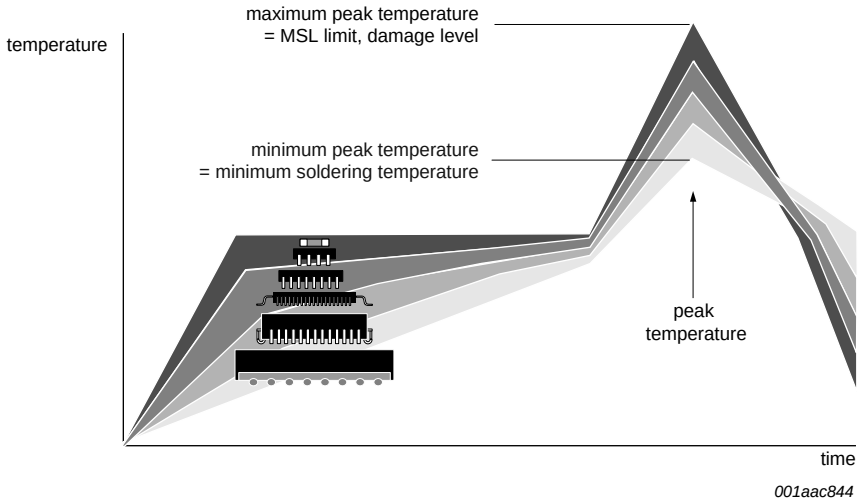

MSL: Moisture Sensitivity Level

Fig 21. Temperature profiles for large and small components

For further information on temperature profiles, refer to Application Note *AN10365 "Surface mount reflow soldering description"*.

18. Soldering of through-hole mount packages

18.1 Introduction to soldering through-hole mount packages

This text gives a very brief insight into wave, dip and manual soldering.

Wave soldering is the preferred method for mounting of through-hole mount IC packages on a printed-circuit board.

18.2 Soldering by dipping or by solder wave

Driven by legislation and environmental forces the worldwide use of lead-free solder pastes is increasing. Typical dwell time of the leads in the wave ranges from 3 seconds to 4 seconds at 250 °C or 265 °C, depending on solder material applied, SnPb or Pb-free respectively.

The total contact time of successive solder waves must not exceed 5 seconds.

The device may be mounted up to the seating plane, but the temperature of the plastic body must not exceed the specified maximum storage temperature ($T_{stg(max)}$). If the printed-circuit board has been pre-heated, forced cooling may be necessary immediately after soldering to keep the temperature within the permissible limit.

18.3 Manual soldering

Apply the soldering iron (24 V or less) to the lead(s) of the package, either below the seating plane or not more than 2 mm above it. If the temperature of the soldering iron bit is less than 300 °C it may remain in contact for up to 10 seconds. If the bit temperature is between 300 °C and 400 °C, contact may be up to 5 seconds.

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18.4 Package related soldering information

Table 13. Suitability of through-hole mount IC packages for dipping and wave soldering

Package	Soldering method	
	Dipping	Wave
CPGA, HCPGA	-	suitable
DBS, DIP, HDIP, RDBS, SDIP, SIL	suitable	suitable[1]
PMFP[2]	-	not suitable

[1] For SDIP packages, the longitudinal axis must be parallel to the transport direction of the printed-circuit board.

[2] For PMFP packages hot bar soldering or manual soldering is suitable.

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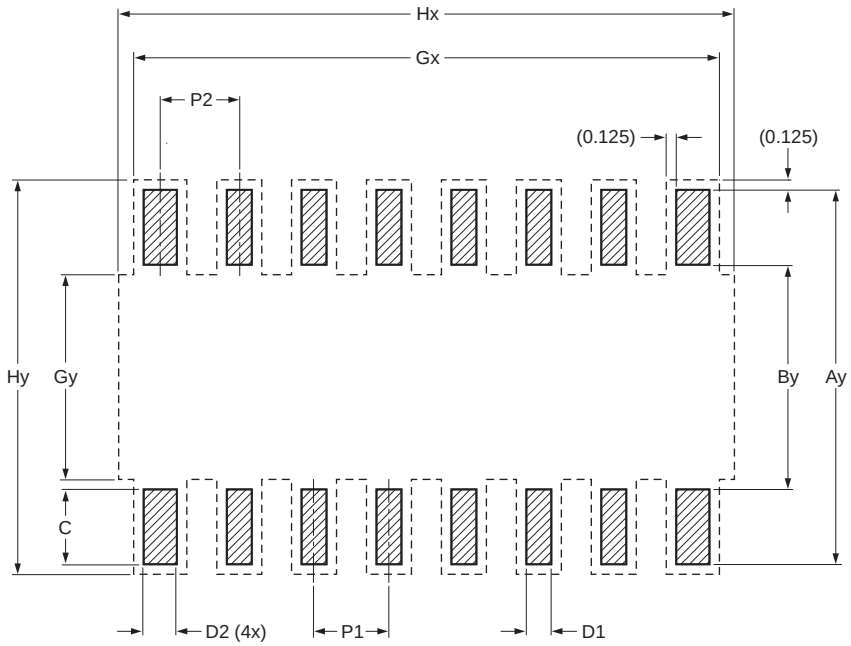
19. Soldering: PCB footprints

Footprint information for reflow soldering of SO16 package **SOT162-1**



Generic footprint pattern
Refer to the package outline drawing for actual layout

solder land

occupied area

DIMENSIONS in mm

P1	P2	Ay	By	C	D1	D2	Gx	Gy	Hx	Hy
1.270	1.320	11.200	6.400	2.400	0.700	0.800	10.040	8.600	11.900	11.450

sot162-1_fr

Fig 22. PCB footprint for SOT162-1 (SO16); reflow soldering

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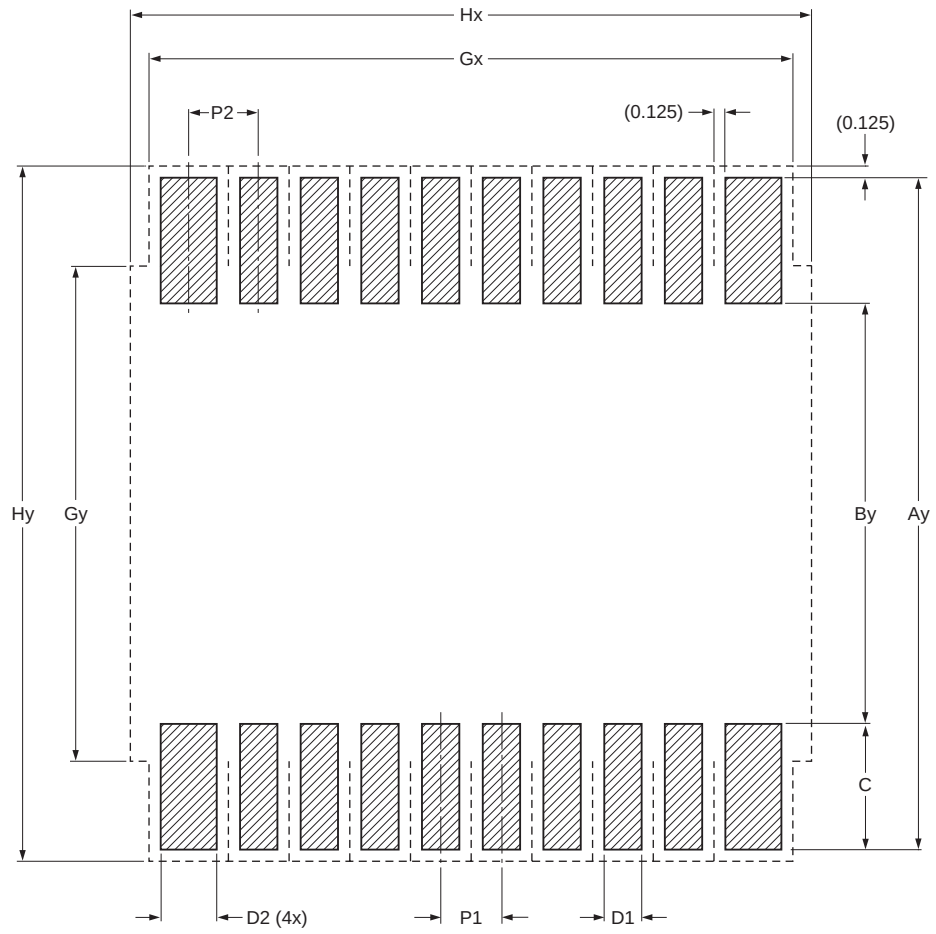
Footprint information for reflow soldering of SSOP20 package **SOT266-1**



DIMENSIONS in mm

P1	P2	Ay	By	C	D1	D2	Gx	Gy	Hx	Hy
0.650	0.750	7.200	4.500	1.350	0.400	0.600	6.900	5.300	7.300	7.450

sot266-1_fr

Fig 23. PCB footprint for SOT266-1 (SSOP20); reflow soldering

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20. Abbreviations

Table 14. Abbreviations

Acronym	Description
CDM	Charged-Device Model
CMOS	Complementary Metal Oxide Semiconductor
I/O	Input/Output
I²C-bus	Inter IC bus
ESD	ElectroStatic Discharge
FF	Flip-Flop
GPIO	General Purpose Input/Output
HBM	Human Body Model
IC	Integrated Circuit
LED	Light Emitting Diode
LP	Low-Pass
PLC	Programmable Logic Controller
POR	Power-On Reset

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21. Revision history

Table 15. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
PCF8574_PCF8574A v.5	20130527	Product data sheet	-	PCF8574 v.4

Modifications:

- The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors.
- Legal texts have been adapted to the new company name where appropriate.
- Electrical parameter letter-symbols and their definitions are updated to conform to NXP presentation standards.
- Section 1 “General description”: updated
- Section 2 “Features and benefits”:
  - third bullet item: appended “with non-overvoltage tolerant I/O held to V_{DD} with 100 μA current source”
  - added (new) fourth and seventh bullet items
  - added sixth bullet item: “Total package sink capability of 80 mA”
  - ninth bullet changed from “(10 μA maximum)” to “(2.5 μA typical)”
  - deleted (old) 11th, 12th and 13th bullet items
- Added (new) eighth bullet item “Mobile devices”
- Table 1 “Ordering information”:
  - Type number corrected from “PCF8574T” to “PCF8574/3”
  - Type number corrected from “PCF8574AT” to “PCF8574AT/3”
  - Type number corrected from “PCF8574TS” to “PCF8574TS/3”
  - Type number corrected from “PCF8574ATS” to “PCF8574ATS/3”
- Added Section 4.1 “Ordering options”
- Figure 4 “Pin configuration for SO16”: updated type numbers (appended “/3”)
- Figure 5 “Pin configuration for SSOP20”: updated type numbers (appended “/3”)
- Section 6.2 “Pin description”: combined DIP16, SO16 and SSOP20 pin descriptions into one table (Table 3)
- Section 7 “Functional description” reorganized
- Section 7.1 “Device address”, first paragraph, fourth sentence: appended “so they must be externally held HIGH or LOW”
- Table 4 “PCF8574 address map” updated: added column for 7-bit hexadecimal address without R/$\overline{W}$
- Table 5 “PCF8574A address map” updated: added column for 7-bit hexadecimal address without R/$\overline{W}$
- Section 8.1 “Quasi-bidirectional I/Os”: re-written and placed before Section 8.4 “Power-on reset”
- added Section 8.2 “Writing to the port (Output mode)”
- added Section 8.3 “Reading from a port (Input mode)”
- Figure 9 “Read mode (input)”: changed symbol “t_{ps}” to “t_{su}”
- Section 8.4 “Power-on reset” re-written
- Section 8.5 “Interrupt output (INT)” re-written
- Figure 10 “Application of multiple PCF8574/74As with interrupt” updated: changed device 16 from “PCF8574” to “PCF8574A”
- Section 9.3 “Acknowledge”, first paragraph, third sentence re-written.
- Added Section 10 “Application design-in information”

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Table 15. Revision history *…continued*

Document ID	Release date	Data sheet status	Change notice	Supersedes
Modifications: (continued)	• Table 7 “Limiting values”: – changed parameter description for symbol I_I from “DC input current” to “input current” – changed parameter description for symbol I_O from “DC output current” to “output current” – changed parameter description for symbol I_{SS} from “supply current” to “ground supply current” – changed symbol “P_O” to “P/out” – added $T_{j(max)}$ limits • Added Section 12 “Thermal characteristics” • Table 9 “Static characteristics”: – table title changed from “DC characteristics” to “Static characteristics” – sub-section “I/Os; P0 to P7”: changed parameter description for symbol $I_{trt(pu)}$ from “transient pull-up current” to “transient boosted pull-up current” – moved sub-section “Port timing” to Table 10 “Dynamic characteristics” – sub-section “Interrupt $\overline{INT}$”: moved sub-sub-section “Timing” to Table 10 “Dynamic characteristics” • Table 10 “Dynamic characteristics”: – sub-section “I²C-bus timing”: deleted symbol/parameter “t_{SW}, tolerable spike width on bus” – sub-section “Port timing”: changed symbol/parameter from “t_{pv}, output data valid time” to “$t_{v(Q)}$, data output valid time” – sub-section “Port timing”: changed symbol/parameter from “t_{su}, input data set-up time” to “$t_{su(D)}$, data input set-up time” – sub-section “Port timing”: changed symbol/parameter from “t_h, input data hold time” to “$t_{h(D)}$, data input hold time” – sub-section “Interrupt $\overline{INT}$”: changed parameter description for symbol $t_{v(INT)}$ from “$\overline{INT}$ output valid time” to “valid time on pin $\overline{INT}$” – sub-section “Interrupt $\overline{INT}$”: changed parameter description for symbol $t_{rst(INT)}$ from “$\overline{INT}$ reset delay time” to “reset time on pin $\overline{INT}$” • Added Section 19 “Soldering: PCB footprints”		
PCF8574 v.4 (9397 750 10462)	20021122	Product specification	-	PCF8574 v.3
PCF8574 v.3 (9397 750 09911)	20020729	Product specification	-	PCF8574 v.2
PCF8574 v.2 (9397 750 01758)	19970402	Product specification	-	PCF8574_PCF8574A v.1
PCF8574_PCF8574A v.1 (9397 750 70011)	199409	Product specification	-	-

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